

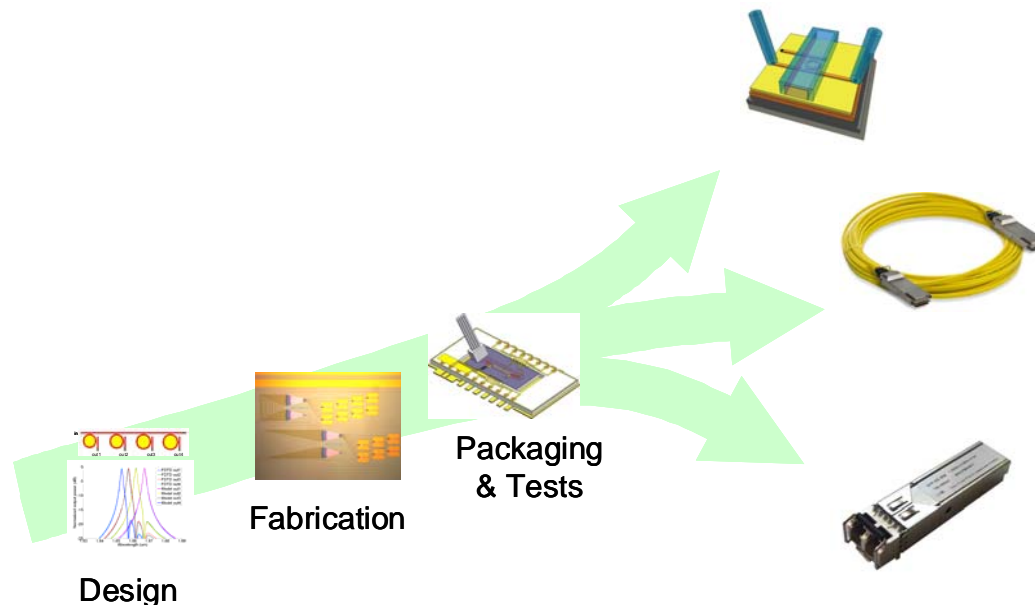


Packaging and tests challenges for industrialization of silicon photonics

23 May 2011, 13:30 – 18:00

Munich

- ◆ Why such a workshop?
 - Silicon photonics market expected to grow very fast in the coming years
 - Much efforts devoted to silicon integration, less on packaging and tests
 - There is room for industrial players all along the value chain



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|-------|--|---|
| 14:00 | State of the art in silicon photonics and technology roadmap | Laurent Fulbert, CEA-LETI |
| 14:20 | Industrial requirements | Bert Offrein, IBM Didier Sauvage, 3S Photonics Henri Porte, Photline Mike Wale, Oclaro Andreas Hakansson, DAS Photonics |
| 16:00 | Coffee break & poster session | |
| 16:30 | ITRS packaging roadmap | Jürgen Wolf, Fraunhofer IZM |
| 16:45 | State of the art and trends in silicon photonics packaging | Lars Zimmermann, TU Berlin |
| 17:00 | Evolution of ePIXfab foundry service | Pieter Dumon, imec |
| 17:15 | Open discussion | |
| 18:00 | End of the workshop | |

Presentations available online very soon